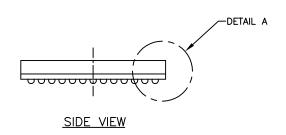
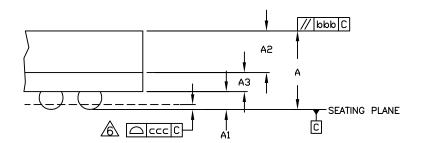


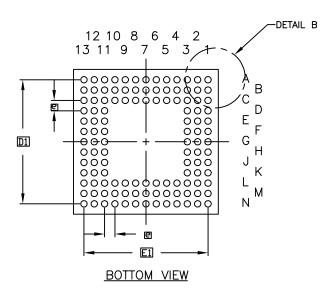
TOP VIEW

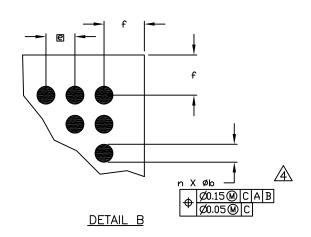




<u>DETAIL A</u>

-DRAWING NOT TO SCALE-







maxim integrated_™

TITLE:
PACKAGE DUTLINE, 120 BALL CTBGA,
7×7×1.1 mm,0.5mm PITCH
APPROVAL DOCUMENT CONTROL NO. REV. 1

21-0899

REV. | I

| DIMENSIONAL REFERENCES | | | |
|------------------------|-----------|------|------|
| REF. | MIN. | N□M. | MAX. |
| Α | 1.00 | 1.12 | 1.20 |
| A1 | 0.16 | 0.21 | 0.26 |
| A2 | 0.65 REF. | | |
| A3 | 0.26 REF. | | |
| D | 7.00 BSC. | | |
| D1 | 6.00 BSC. | | |
| E | 7.00 BSC. | | |
| E1 | 6.00 BSC. | | |
| b | 0.27 | 0.31 | 0.37 |
| ممم | 0.10 | | |
| bbb | 0.10 | | |
| ccc | 0.08 | | |
| е | 0.50 BSC. | | |
| f | ı | 0.50 | - |
| М | 13 | | |
| n | 120 | | |
| PKG. CODE | X12077+1 | | |

NOTES:

- 1. ALL DIMENSIONS ARE IN MILLIMETERS UNLESS OTHERWISE SPECIFIED.
- 2. DIMENSIONING & TOLERANCING CONFORM TO ASME Y14.5M-1994.
- 3. DRAWING CONFORMS TO JEDEC MO-195D.
- $\cancel{4}$. $\cancel{6}$ is measurable at the maximum solder ball diameter.
- 5. 'M' REPRESENTS THE BASIC SOLDER BALL MATRIX SIZE AND SYMBOL 'n' IS THE NUMBER OF BALLS AFTER DEPOPULATING.
- 6 DIMENSION 'ccc' IS MEASURED PARALLEL TO PRIMARY DATUM C.
- 7. PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
- 8. WARPAGE SHALL NOT EXCEED 0.10MM.
- 9. THE OVERALL PACKAGE THICKNESS "A" ALREADY CONSIDERS COLLAPSED BALLS
- 10 MARKING IS FOR PACKAGE ORIENTATION REFERENCE ONLY.
- 11. MATERIAL MUST COMPLY WITH BANNED AND RESTRICTED SUBSTANCES SPEC# 10-0131. SUBSTRATE MATERIAL BASE IS BT RESIN. GREEN, LEADFREE SUBSTRATE.
- 12. ALL DIMENSIONS APPLY TO PHFREE (+) PKG. CODE ONLY.



PACKAGE DUTLINE, 120 BALL CTBGA, 7×7×1.1 mm,0.5mm PITCH

APPROVAL

DOCUMENT CONTROL NO. 21-0899

REV. 2